









Release Date: 22 September 2015 Version: A1.1





- ► PTH Lamp
- ➤ 3mm Cylindrical 3.8t
- ► Green (570nm)

NOG02L44R (Bulk) N0G02L44RT (Taping)



3mm Cylindrical Lamp





FEATURES:

Package: PTH Lamp 3mm Cylindrical 3.8t

Forward Current: 20mA Forward Voltage (typ.): 2.1V

Luminous Intensity (typ.): 52mcd @20mA

Colour: Green Wavelength: 570nm Viewing angle: 150°

Materials:

Die: AlInGaP

Resin: Epoxy (Green Clear) Operating Temperature: -40~+85°C Storage Temperature: -40~+100°C

Grouping parameters:

- Forward voltage
- Luminous intensity
- Wavelength
- Soldering methods: Hand; Wave Soldering (DIP)
- Preconditioning: acc. to JEDEC Level 3 Packing: 500pcs/Bulk; 2000pcs/Taping

3 mm Cylindrical Lamp

APPLICATIONS:

- Indicator
- Switch
- Signal Light



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/10@1KHz	I _{FP}	100	mA
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	85	mW
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

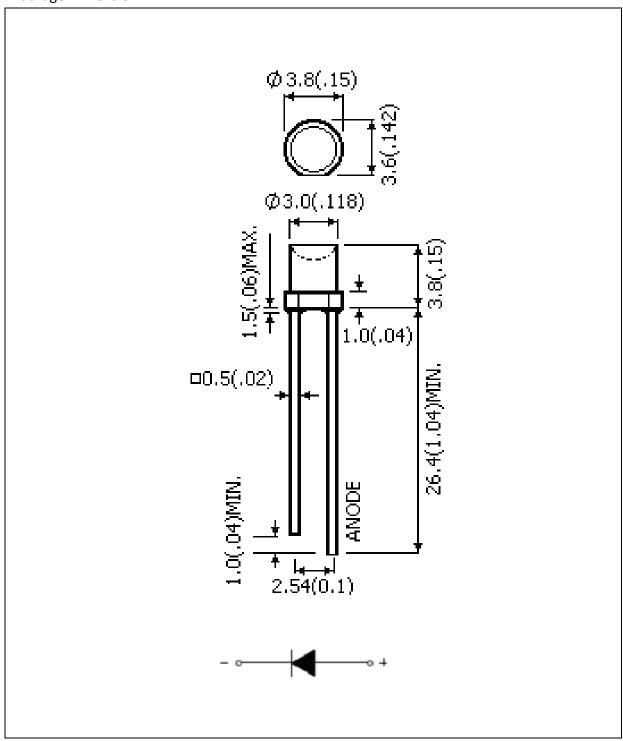
Darameter	Cumbal	Values			Unit	Test
Parameter Symbol	Зуппоп	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V_{F}	1.7	2.1	2.6	V	I _F =20mA
Luminous Intensity	I _V	25	52	78	mcd	I _F =20mA
Dominant Wavelength	$\lambda_{\scriptscriptstyle D}$	567	572	577	nm	I _F =20mA
Peak Wavelength	λ_{P}		570		nm	I _F =20mA
Spectral Line H-Width	Δλ		19		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		150		deg	I _F =20mA

^{1.} Luminous intensity (I_V) ±15%, Forward Voltage (V_F) ±0.1V



OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.25mm, unless otherwise noted.



BINNING GROUPS:

Forward Voltage Classifications ($I_F = 20mA$):

Code	Min.	Max.	Unit
V17	1.7	2.6	V

Luminous Intensity Classifications ($I_F = 20$ mA):

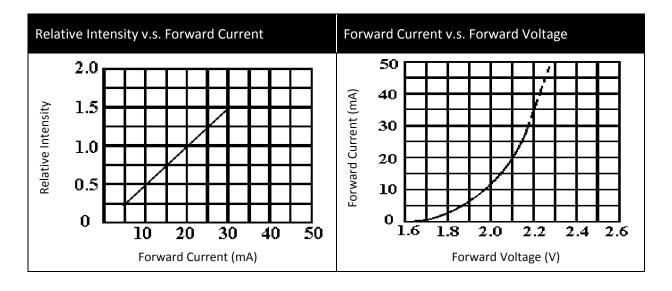
Code	Min.	Max.	Unit
L25	25	78	mcd

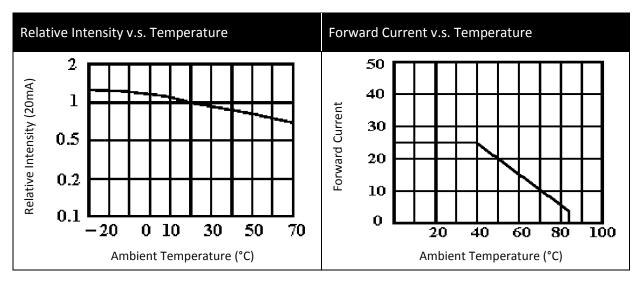
Wavelength Classifications ($I_F = 20 \text{mA}$):

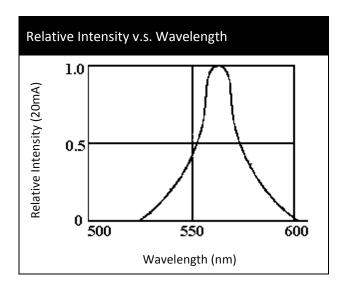
Code	Min.	Max.	Unit
G567	567	572	200
G572	572	577	nm



ELECTRO-OPTICAL CHARACTERISTICS:







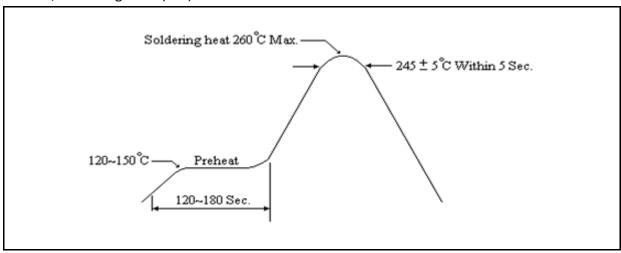


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 300°C Max. (25W Max.).
- Soldering Time: 3 seconds ± 1 sec.
- Maximum reflow soldering: 1 time.

Wave / Soldering Heat (DIP):



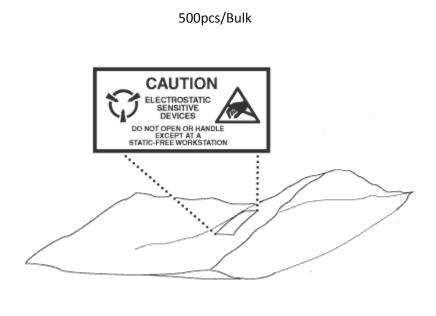
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.

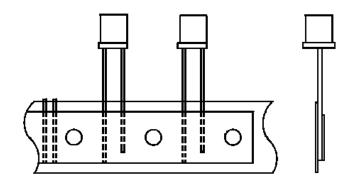


PACKING SPECIFICATION:

Reel Dimension:



2000pcs/Taping





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

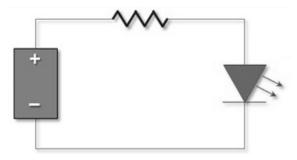
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	04/08/2015	Datasheet set-up.
A1.1	21/09/2015	Update solder profile.